

Docket No.: 4459-050



# 9/A  
6-25-03  
Moller  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Jen-Kuang FANG et al.

Application No. 09/883,216

Filed: June 19, 2001

Group Art Unit: 2811

Examiner: Nitin Parekh

For: SEMICONDUCTOR DEVICE HAVING BUMP ELECTRODES

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are submitted in response to the Official action dated March 19, 2003.

IN THE CLAIMS:

✓  
Please cancel claims 5-6 without prejudice or disclaimer.

Please amend the remaining claims as follows:

1. (Amended) A method of forming a semiconductor device having a bump electrode, the method comprising the steps of:

providing an aluminum contact pad on a substrate, at least a portion of the aluminum contact pad being exposed through a dielectric layer on the substrate;

forming an aluminum layer on the dielectric layer and the portion of the aluminum contact pad exposed through the dielectric layer;

forming a nickel-vanadium layer on the aluminum layer;

RECEIVED  
JUN 19 2003  
TECHNOLOGY CENTER 2800

A1